



深圳市丹宇电子有限公司
Best Technology Co., Limited

产品规格书 (DBC)

Product Specification (DBC)

目录

1. 材料介绍 Material
 - 1.1. 瓷片 Ceramic
 - 1.2. 物料厚度组合 Material thickness combination
2. 覆铜衬板 DBC Substrate
 - 2.1. 耐高温特性 Temperature resistance characteristics
 - 2.2. 温度循环 Temperature cycle
 - 2.3. 其他物理特性 Other physical properties
 - 2.4. 交付样式 Delivery method
3. 设计特性 Design features
 - 3.1. 铜层 Copper layer design
 - 3.1.1. 厚度公差 Thickness tolerance
 - 3.1.2. 线宽线距 Line width line spacing
 - 3.1.3. 侧蚀量 Sidewall of etched pattern
 - 3.1.4. 正背面铜箔对位公差 Alignment tolerance of copper on Top/Bottom
 - 3.1.5. 铜自由区 Copper free area
 - 3.1.6. 钉孔 Dimple
 - 3.2. 铜层表面处理 Copper surface treatment
 - 3.3. 阻焊 Solder mask
 - 3.4. 激光切割 Laser cutting
 - 3.4.1. 划线 Scribing
 - 3.4.2. 孔 Holes
 - 3.4.3. 陶瓷崩边 Chipping
 - 3.5. 其他设计特性 Other design features

Thanks for your visit! To ensure that our valuable materials are accessible to real people like you, please E-mail to sales@bestpcbs.com or send Skype to **besttech8010**, we will be in touch with you!

(This helps us prevent automated bots and unauthorized access. Rest assured, your information will only be used to send you the download link and occasional updates. We appreciate your understanding and cooperation.)